



## Final Product Change Notification

201401007F01

**Issue Date:** 16-Jan-2014  
**Effective Date:** 16-Apr-2014

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# QUALITY

### Management Summary

HT2DC20S20 transponder products that are not compliant with RoHS will be replaced to meet RoHS.  
Proven 1-to-1 replacement types are available, where the sub-package is changed.

### Change Category

<input type="checkbox"/> Wafer Fab process	<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

## HT2DC20 - Introduction of Pb free stick transponder

### Details of this Change

Subpackage change from version BA4 to CA5. This includes change of leadframe layout, die thickness and wire diameter. Internal connections of passive components are realized with leadfree solder to achieve RoHS compliancy. As a consequence to the subpackage change the transponder's package outline (SOT385-1) will not change. Furthermore, the internal resonant capacitor type (size and temperature characteristic) will change.

### Why do we Implement this Change

The change of the sub-package is done in line with the requirements of the legislation (RoHS) to ban lead (Pb) from electronic components, and is, thus, increasing the environmental friendliness of the affected NXP products. The sub-package CA5 of the replacements types is already in production for all other contactless transponder types, this change is also a measure of standardization and provides a future-proof assembly configuration. Electrical and mechanical characteristics, including package outer dimensions are maintained.

## Identification of Affected Products

Product identification does not change

## Product Availability

### Sample Information

Samples are available upon request

### Production

Planned first shipment 01-May-2014

## Impact

no impact to the product's functionality anticipated.

### Data Sheet Revision

No impact to existing datasheet

### Disposition of Old Products

Existing inventory will be shipped until depleted

## Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 15-Feb-2014.

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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